# 700V N-Channel MOSFET

#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



<b>Device Marking and Package Information</b>						
Device	Package	Marking				
CS3N70F	TO-220F	CS3N70F				
CS3N70P	TO-220	CS3N70P				
CS3N70U	TO-251	CS3N70U				
CS3N70D	TO-252	CS3N70D				

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted								
Devementer	Oh. ad	Value				11		
Parameter	Symbol	TO-220F	TO-220	TO-251	TO-252	Unit		
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	700			V			
Continuous Drain Current	I <sub>D</sub>	3			Α			
Pulsed Drain Current (note1)	I <sub>DM</sub>	12				Α		
Gate-Source Voltage	V <sub>GSS</sub>	±30			V			
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	28.8			mJ			
Avalanche Current (note1)	I <sub>AS</sub>	2.4			Α			
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	17.3			mJ			
Power Dissipation (T <sub>C</sub> = 25°C)	$P_{D}$	36 75		W				
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150			°C			

Thermal Resistance							
Baramatar	Symbol	Value				11	
Parameter		TO-220F	TO-220	TO-251	TO-252	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	3.47	1.67		K/W		
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	60		rv/ VV		

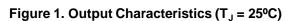


<b>Specifications</b> $T_J = 25^{\circ}$ C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Value			11-4:4		
	Syllibol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	700			V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 700, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V		
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.5A		3.5	4.1	Ω		
Dynamic								
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ ,		393		pF		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25V$ ,		39				
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		4				
Total Gate Charge	$Q_g$			12.4		nC		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 560V, I_{D} = 3.0A, V_{GS} = 10V$		2				
Gate-Drain Charge	$Q_{gd}$	65		6.8				
Turn-on Delay Time	t <sub>d(on)</sub>			35		ns		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 350V, I_D = 3.0A,$		8.4				
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		72.8				
Turn-off Fall Time	t <sub>f</sub>			30.4				
Drain-Source Body Diode Character	istics							
Continuous Body Diode Current	Is	T			3	А		
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			12			
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 1.5\text{A}, V_{GS} = 0\text{V}$			1.4	V		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 3.0A,$		579		ns		
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		0.81		μC		

#### **Notes**

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

#### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



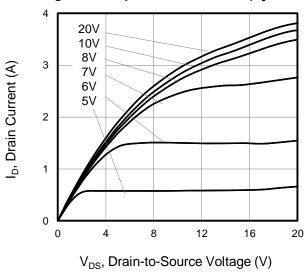


Figure 2. Body Diode Forward Voltage

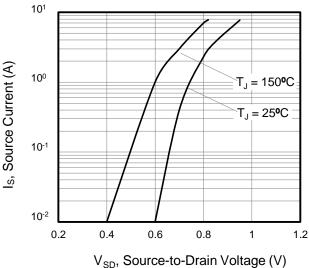


Figure 3. Drain Current vs. Temperature



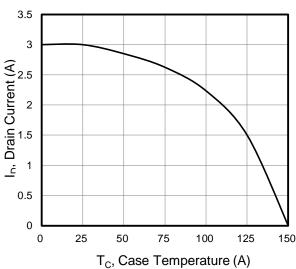


Figure 4. Power Dissipation vs. Temperature

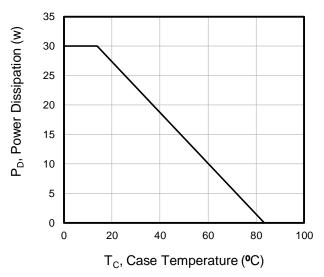


Figure 5. Transfer Characteristics

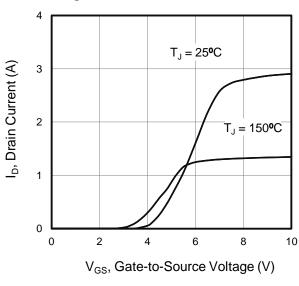
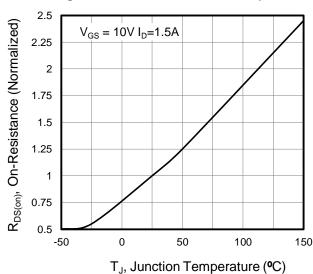


Figure 6. On-Resistance vs. Temperature



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

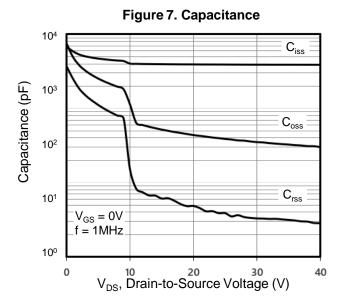


Figure 8. Gate Charge

V<sub>DD</sub> = 120V
V<sub>DD</sub> = 350V
V<sub>DD</sub> = 560V
V<sub>DD</sub> =

Figure 9. Transient Thermal Impedance TO-220F

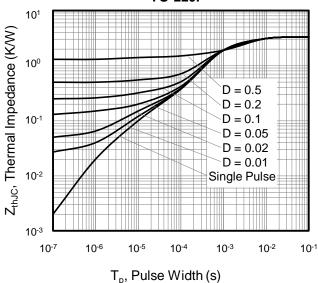


Figure 10. Transient Thermal Impedance TO-220, TO-251,TO-252

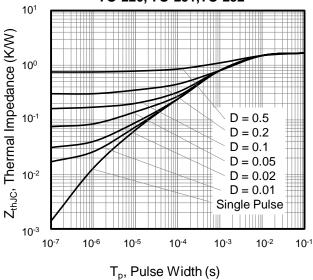


Figure A: Gate Charge Test Circuit and Waveform

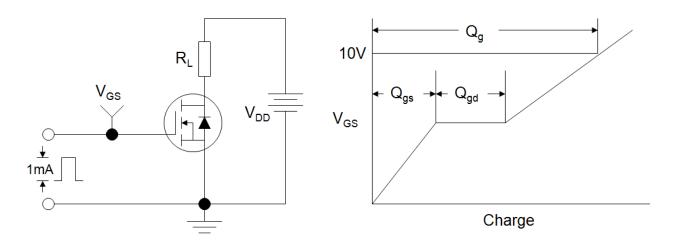


Figure B: Resistive Switching Test Circuit and Waveform

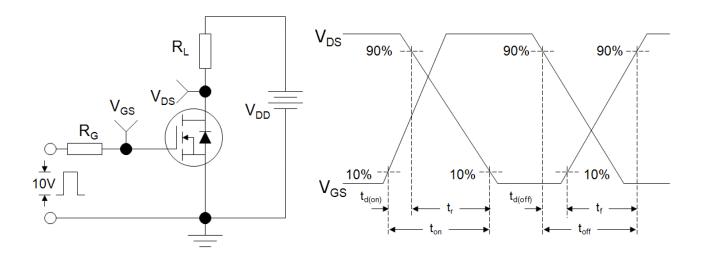
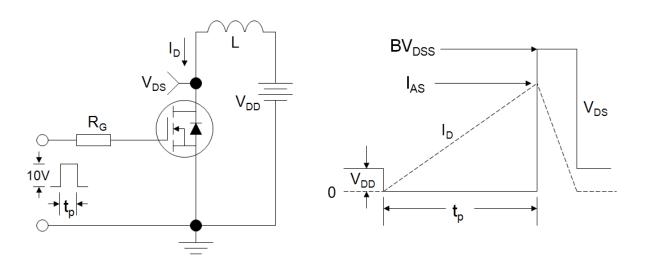
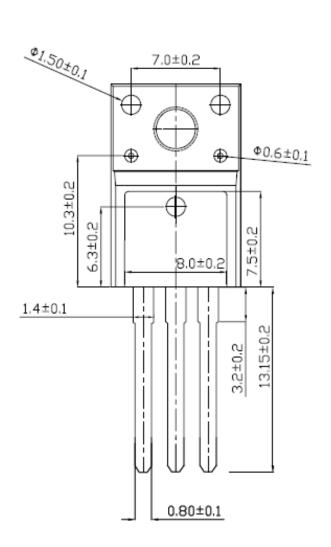


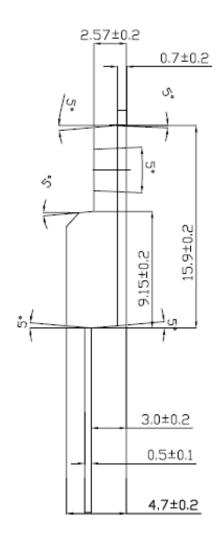
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





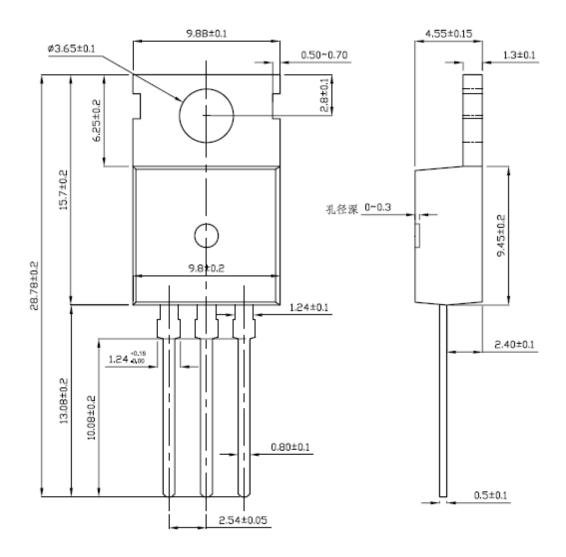
# **TO-220F**





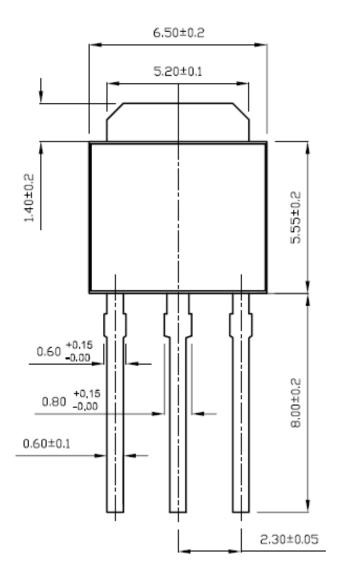


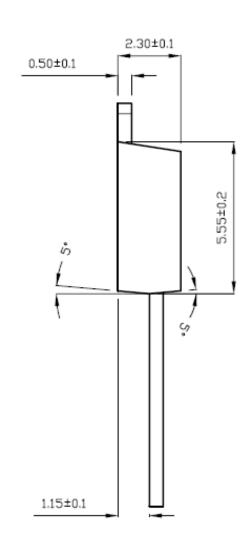
# **TO-220**





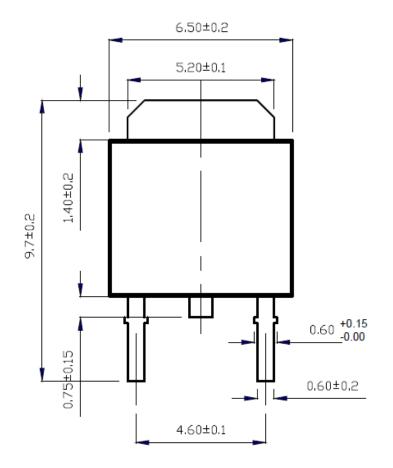
**TO-251** 

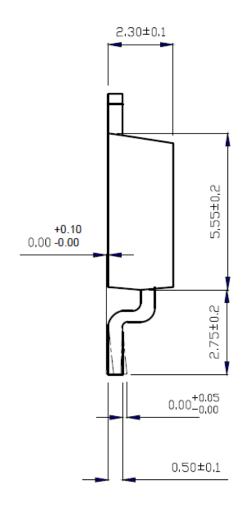






**TO-252** 







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